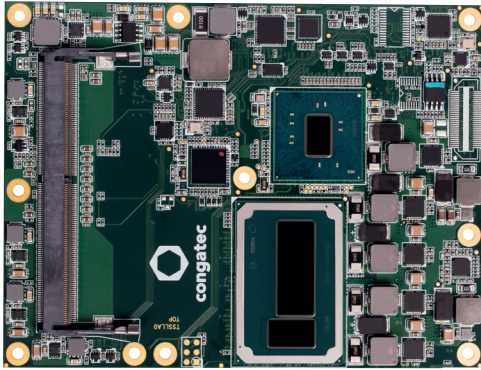


SERVER-CLASS EMBEDDED PERFORMANCE

conga-TS170

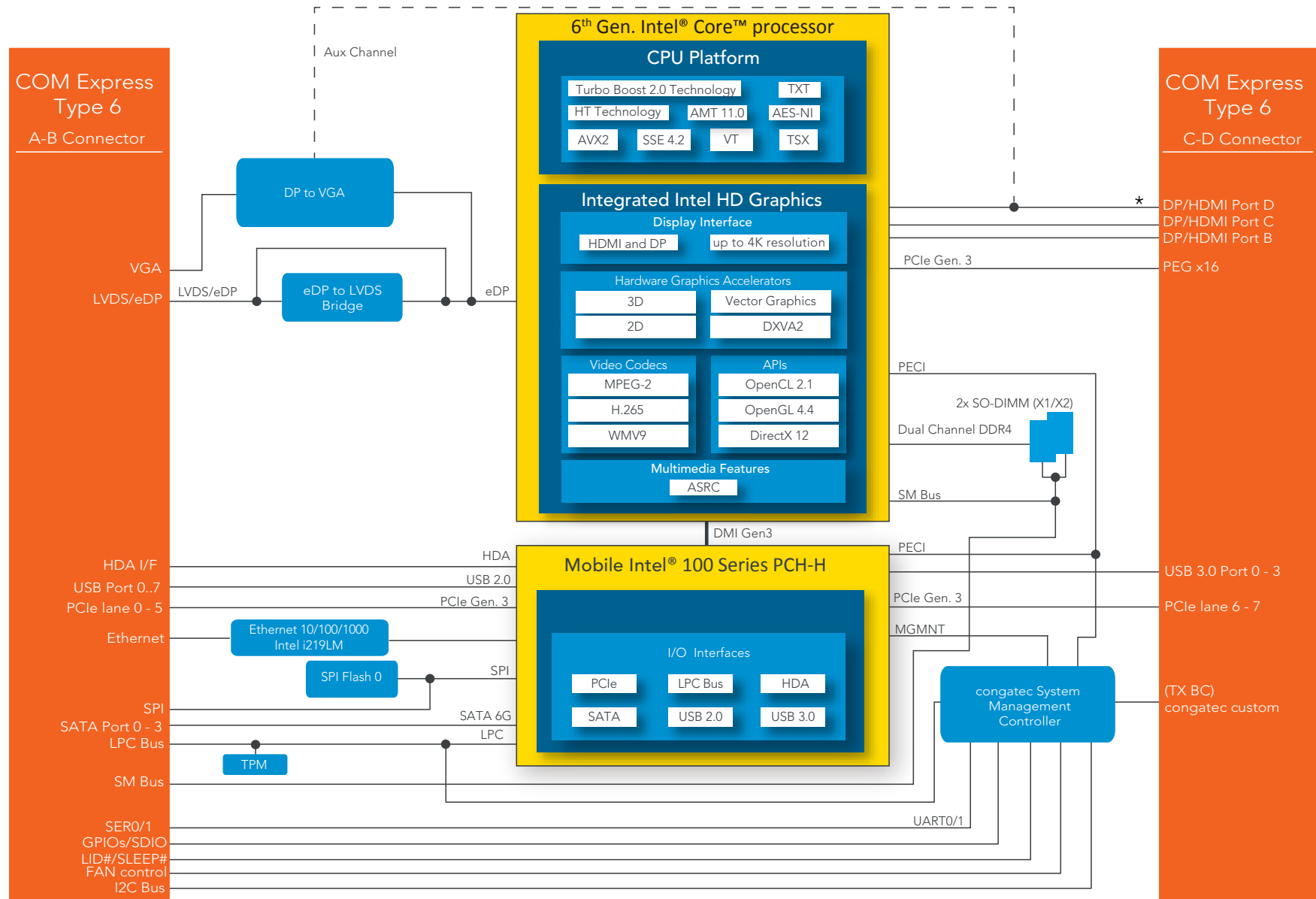


- 6th Generation Intel® Core™ processor
- Intel® Gen9 HD Graphics with HEVC (H.265) support up to Intel® Iris™ Pro Graphics P580
- ECC memory support
- Up to 32 GByte dual channel DDR4 memory
- Intel® Xeon® processors for data center applications



Formfactor	COM Express® Basic, (95 x 125 mm), Type 6 Connector Pinout		
CPU	Intel® Xeon® E3-1578LV5 Intel® Xeon® E3-1558LV5 Intel® Xeon® E3-1515MV5 Intel® Xeon® E3-1505MV5 Intel® Xeon® E3-1505LV5 Intel® Core™ i7-6820EQ Intel® Core™ i7-6822EQ Intel® Core™ i5-6440EQ Intel® Core™ i5-6442EQ Intel® Core™ i3-6100E Intel® Core™ i3-6102E Intel® Celeron® G3900E Intel® Celeron® G3902E	Quad Core Quad Core Quad Core Quad Core Quad Core Quad Core Quad Core Quad Core Dual Core Dual Core Dual Core Dual Core	2.0 / 3.4 GHz 1.9 / 3.3 GHz 2.8 / 3.7 GHz 2.8 / 3.7 GHz 2.0 / 2.8 GHz 2.8 / 3.5 GHz 2.0 / 2.8 GHz 2.7 / 3.7 GHz 1.9 / 2.7 GHz 2.7 GHz 1.9 GHz 2.4 GHz 1.6 GHz
DRAM	2 Sockets, SO-DIMM DDR4 up to 2133 MT/s and 32GByte dual channel, Intel® Xeon® and Intel® Core® i3 with ECC support		
Chipset	Mobile Intel® 100 Series Chipset		
Ethernet	Intel® i219-LM GbE LAN Controller with AMT 11 support		
I/O Interfaces	8x PCI Express™ gen. 3.0 lanes 4x Serial ATA® Gen 3 4x USB 3.0 (XHCI) 8x USB 2.0 (XHCI) 1x PEG x16 Gen 3 LPC bus (no DMA) I²C bus (fast mode, 400 kHz, multi-master) 2x UART		
Sound	Digital High Definition Audio Interface with support for multiple audio codecs		
Graphics	Intel® Gen9 HD Graphics Engine with OpenCL 2.0, OpenGL 4.3 and DirectX12 (for Windows 10) support up to three independent displays: HDMI 1.4a / DisplayPort 1.2 / eDP 1.3 High performance hardware MPEG-2 decoding WMV9 (VC-1) and H.265 (HEVC) support Blu-ray support @ 40 MBit/s HEVC, VP8, VP9 and VDENC encoding		
LVDS (eDP optional)	Dual channel LVDS transmitter, Supports flat panels 2x24 Bit interface VESA and openLDI colour mappings resolutions up to 1920x1200 Automatic Panel Detection via EDID/EPI		
Digital Display Interface (DDI)	3x TMDS (HDMI) / DisplayPort 1.2 with support for Multi-Stream Transport (MST) resolutions up to 4k VGA		
congatec Board Controller	Multi Stage Watchdog non-volatile User Data Storage Manufacturing and Board Information Board Statistics BIOS Setup Data Backup I²C bus (fast mode, 400 kHz, multi-master) Power Loss Control		
Embedded BIOS Features	AMI Aptio® UEFI 2.x firmware 8/16 MByte serial SPI firmware flash		
Security	The conga-TS170 can be optionally equipped with a discrete "Trusted Platform Module" (TPM 1.2 / 2.0). It is capable of calculating efficient hash and RSA algorithms with key lengths up to 2,048 bits and includes a real random number generator. Security sensitive applications such as gaming and e-commerce will benefit also with improved authentication, integrity and confidence levels.		
Power Management	ACPI 4.0 with battery support		
Operating Systems	Microsoft® Windows 10 Microsoft® Windows IoT Enterprise Microsoft® Windows 7 Linux Microsoft® Windows embedded Standard		
Power Consumption	See User's Guide for full details		
Temperature	Operating: 0 .. +60°C Storage: -20 .. +80°C		
Humidity	Operating: 10 - 90% r. H. non cond. Storage: 5 - 95% r. H. non cond.		
Size	95 x 125 mm (3.74" x 4.92")		

conga-TS170 | Block diagram



* DDI port D supports only HDMI if VGA is enabled.

conga-TS170 | Order Information

Article	PN	Description
conga-TS170/E3-1578LV5	045913	COM Express Type 6 Basic module with Skylake-H Intel® Xeon® E3-1578L V5 quad core processor with 2.0GHz up to 3.4GHz, 8MB L2 cache, GT4 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset CM236 with ECC memory support
conga-TS170/E3-1558LV5	045914	COM Express Type 6 Basic module with Skylake-H Intel® Xeon® E3-1558L V5 quad core processor with 1.9GHz up to 3.3GHz, 8MB L2 cache, GT4 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset CM236 with ECC memory support
conga-TS170/E3-1515MV5	045912	COM Express Type 6 Basic module with Skylake-H Intel® Xeon® E3-1515M V5 quad core processor with 2.8GHz up to 3.7GHz, 8MB L2 cache, GT4 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset CM236 with ECC memory support
conga-TS170/E3-1505MV5	045906	COM Express Type 6 Basic module with Skylake-H Intel® Xeon® E3-1505M V5 quad core processor with 2.8GHz up to 3.7GHz, 8MB L2 cache, GT2 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset CM236 with ECC memory support
conga-TS170/E3-1505LV5	045907	COM Express Type 6 Basic module with Skylake-H Intel® Xeon® E3-1505L V5 quad core processor with 2.0GHz up to 2.8GHz, 8MB L2 cache, GT2 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset CM236 with ECC memory support
conga-TS170/i7-6820EQ	045900	COM Express Type 6 Basic module with Skylake-H Intel® Core™ i7-6820EQ quad core processor with 2.8GHz up to 3.5GHz, 8MB L2 cache, GT2 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset QM170
conga-TS170/i7-6822EQ	045901	COM Express Type 6 Basic module with Skylake-H Intel® Core™ i7-6822EQ quad core processor with 2.0GHz up to 2.8GHz, 8MB L2 cache, GT2 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset QM170
conga-TS170/i5-6440EQ	045902	COM Express Type 6 Basic module with Skylake-H Intel® Core™ i5-6440EQ quad core processor with 2.7GHz up to 3.4GHz, 6MB L2 cache, GT2 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset QM170
conga-TS170/i5-6442EQ	045903	COM Express Type 6 Basic module with Skylake-H Intel® Core™ i5-6442EQ quad core processor with 1.9GHz up to 2.7GHz, 6MB L2 cache, GT2 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset QM170
conga-TS170/i3-6100E ECC	045908	COM Express Type 6 Basic module with Skylake-H Intel® Core™ i3-6100E dual core processor with 2.7GHz, 3MB L2 cache, GT2 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset CM236 with ECC memory support
conga-TS170/i3-6102E ECC	045909	COM Express Type 6 Basic module with Skylake-H Intel® Core™ i3-6102EQ dual core processor with 1.9GHz, 3MB L2 cache, GT2 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset CM236 with ECC memory support
conga-TS170/i3-6100E	045904	COM Express Type 6 Basic module with Skylake-H Intel® Core™ i3-6100E dual core processor with 2.7GHz, 3MB L2 cache, GT2 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset HM170
conga-TS170/i3-6102E	045905	COM Express Type 6 Basic module with Skylake-H Intel® Core™ i3-6102EQ dual core processor with 1.9GHz, 3MB L2 cache, GT2 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset HM170
conga-TS170/G3900E	045910	COM Express Type 6 Basic module with Skylake-H Intel® Celeron® G3900E dual core processor with 2.4GHz, 2MB L2 cache, GT1 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset HM170
conga-TS170/G3902E	045911	COM Express Type 6 Basic module with Skylake-H Intel® Celeron® G3902E dual core processor with 1.6GHz, 2MB L2 cache, GT1 graphics and 2133MT/s dual channel DDR4 memory interface, Chipset HM170

Article	PN	Description
conga-TS170/HSP-HP-B	045934	Standard heatspreader for high performance COM Express modules conga-TS170/TS175 with integrated heat pipes. All standoffs are with 2.7mm bore hole.
conga-TS170/HSP-HP-T	045935	Standard heatspreader for high performance COM Express modules conga-TS170/TS175 with integrated heat pipes. All standoffs are M2.5mm thread.
conga-TS170/CSP-HP-B	045932	Standard passive cooling solution for high performance COM Express modules conga-TS170/TS175 with integrated heat pipes, 15mm silver fins and 21mm overall heat sink height. All standoffs are with 2.7mm bore hole.
conga-TS170/CSP-HP-T	045933	Standard passive cooling solution for high performance COM Express modules conga-TS170/TS175 with integrated heat pipes, 15mm silver fins and 21mm overall heat sink height. All standoffs are M2.5mm thread.
conga-TS170/CSA-HP-B	045930	Standard active cooling solution for high performance COM Express modules conga-TS170/TS175 with integrated heat pipes, 15mm silver fins, 21mm overall heat sink height and integrated 12V fan. All standoffs are with 2.7mm bore hole.
conga-TS170/CSA-HP-T	045931	Standard active cooling solution for high performance COM Express modules conga-TS170/TS175 with integrated heat pipes, 15mm silver fins, 21mm overall heat sink height and integrated 12V fan. All standoffs are M2.5mm thread.
DDR4-SODIMM-2400 (4GB)	068790	4 GByte DDR4 SODIMM memory module with 2400 MT/s
DDR4-SODIMM-2400 (8GB)	068791	8 GByte DDR4 SODIMM memory module with 2400 MT/s
DDR4-SODIMM-2400 (16GB)	068792	16 GByte DDR4 SODIMM memory module with 2400 MT/s
DDR4-SODIMM-2400 ECC (4GB)	068795	4 GByte DDR4 ECC SODIMM memory module with 2400 MT/s
DDR4-SODIMM-2400 ECC (8GB)	068796	8 GByte DDR4 ECC SODIMM memory module with 2400 MT/s
DDR4-SODIMM-2400 ECC (16GB)	068797	16 GByte DDR4 ECC SODIMM memory module with 2400 MT/s
conga-TEVAL	065800	Evaluation carrier board for Type 6 COM-Express-modules
conga-LDVI/EPI	011115	LVDS to DVI converter board for digital flat panels with onboard EEPROM
COMe-carrier-board-Socket-5	400007	Connector for COM-Express carrier boards, height 5mm, packing unit 4 pieces
COMe-carrier-board-Socket-8	400004	Connector for COM-Express carrier boards, height 8mm, packing unit 4 pieces